

ABSTRACT

TEMPORARY ADHESIVE CONTAINING PHENYL GROUP-CONTAINING
POLYSILOXANE

5

There is provided a temporary adhesive that has excellent spin coating properties of a circuit side of a wafer and a support, and excellent heat resistance when the circuit side of the wafer or the support is attached to an adhesion layer or when a rear surface of the wafer is processed, and is capable of easily separating the circuit side of the wafer from the support after polishing the rear surface of the wafer, and simply removing the adhesive attached to the wafer or the support after the separation; a layered body using the temporary adhesive; and a processing method using the layered body. An adhesive for separatably attaching a support to a circuit side of a wafer to process a rear surface of the wafer, the adhesive comprising a component (A) that is cured by a hydrosilylation reaction and a component (B) containing a phenyl group-containing polyorganosiloxane, wherein a ratio in % by mass of the component (A) to the component (B) is 95:5 to 30:70. A separation method comprising applying the adhesive onto a first body to form an adhesion layer, attaching a second body to the adhesion layer, heating the adhesion layer from a side of the first body to cure the adhesive to form a layered body, processing the layered body, and carrying out separation between the adhesion layer, and the first body and the second body. The processing may be polishing the rear surface of the wafer.

[No figure]